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Address to:
Box CPA
Assistant Commissioner for Patents
Washington, D.C. 20231

Attorney's Docket No. MCSP-101

First Named Inventor Donald Malcolm MacIntyre
Examiner: D. Wille
Art Unit: 2814

**CONTINUED PROSECUTION APPLICATION (CPA)
REQUEST TRANSMITTAL**

Submit an original and a duplicate of transmittal for fee processing.
(Only for Continuation or Divisional applications under 37 CFR 1.53(d))

CERTIFICATION UNDER 37 CFR § 1.10

I hereby certify that this New Application and the documents referred to as enclosed herein are being deposited with the United States Postal Service on this date OCTOBER 10, 2000, in an envelope bearing "Express Mail Post Office To Addressee" Mailing Label Number EL254114001US addressed to: Box CPA, Assistant Commissioner for Patents, Washington, D.C. 20231.

SUSAN OZANNE

(Name of person mailing paper)

Susan Ozanne
(Signature)

Sir:

This is a request for filing a
 X continuation
 divisional application

under 37 CFR 1.53(d) (continued prosecution application (CPA)) of prior application number 09/045,507 filed on March 20, 1998, entitled CHIP SCALE PACKAGES.

NOTES

FILING QUALIFICATIONS: The prior application identified above must be a nonprovisional application that is either: (1) complete as defined by 37 CFR 1.51(b), or (2) the national stage of an international application in compliance with 35 U.S.C. 371.

C-I-P NOT PERMITTED: A continuation-in-part application cannot be filed as a CPA under 37 CFR 1.53(d), but must be filed under 37 CFR 1.53(b).

EXPRESS ABANDONMENT OF PRIOR APPLICATION: The filing of this CPA is a request to expressly abandon the prior application as of the filing date of the request for the CPA. 37 CFR 1.53(b) must be used to file a continuation, divisional, or continuation-in-part of an application that is not to be abandoned.

ACCESS TO PRIOR APPLICATION: The filing of this CPA will be construed to include a waiver of confidentiality by the applicant under 35 U.S.C. 122 to the extent that any member of the public who is entitled under the provisions of 37 CFR 1.14 to access to, copies of, or information concerning, the prior application may be given similar access to, copies of, or similar information concerning, the other application or applications in the file jacket.

35 U.S.C. 120 STATEMENT: In a CPA, no reference to the prior application is needed in the first sentence of the specification and none should be submitted. If a sentence referencing the prior application is submitted, it will not be entered. A request for a CPA is the specific reference required by 35 U.S.C. 120 and to every application assigned the application number identified in such request. 37 CFR 1.78(a).

1. Enter the unentered amendment previously filed on in the prior nonprovisional

1 FC:231 355.00 OF
2 FC:203 279.00 OF
3 FC:204 135.00 OF

PATENT & TRADEMARK

3. This application is filed by fewer than all of the inventors named in the prior application, 37 CFR 1.53(d)(4).

DELETE the following named inventor(s) named in the prior nonprovisional application:

-
-

4. **MAINTENANCE OF COPENDENCY OF PRIOR APPLICATION**

(This item must be completed and the necessary papers filed in the prior application if the period set in the prior application has run).

[X] A petition and fee for extension of time has been filed to extend the term in the pending prior application until November 8, 2000.

[] A copy of the petition for extension of time in the prior application is attached.

5. A new power of attorney or authorization of agent is enclosed.

6. An Information Disclosure Statement (IDS) is enclosed, including a PTO-1449 and copies of references.

7. X Assignment of the invention to MicroCSP, Inc. is attached (including Form PTO-1595).

8. X Return Receipt Postcard (MPEP 503 -- should be specifically itemized)

PAYMENT OF FEES

CLAIMS	NUMBER FILED	NUMBER EXTRA	RATE	BASIC FEE (\$710)
Total Claims (37 CFR 1.16(c))	51 - 20	* 31	x \$18.00	558
Independent Claims	3 - 3	* 0	x \$80.00	0
<u>X</u> Multiple dependent claim(s), if any			\$270.00	270

*If less than zero, enter "0".

Filing Fee Calculation \$1538

50% Filing Fee Reduction (if applicable) \$769

9. **Small Entity Status**

a. A small entity statement is enclosed.

b. X A small entity statement was filed in the prior nonprovisional application and such status is still proper and desired.

c. is no longer claimed.

10. **Payment of Fees**

X Check(s) in the amount of \$1004.00 (\$769 for filing fee, \$40 for assignment recordation and \$195 for 2 month extension) enclosed.

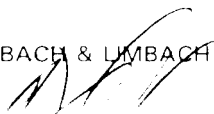
 Charge Account No. 12-1420 in the amount of \$.

A duplicate of this transmittal is attached.

11. X **Authorization to Charge Additional Fees**

The Commissioner is hereby authorized to charge any additional fees (or credit any overpayment) associated with this communication and which may be required under 37 CFR § 1.16 or § 1.17 to Account No. 12-1420. **A duplicate of this transmittal is attached.**

LIMBACH & LIMBACH L.L.P.





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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re CPA of
DONALD MALCOLM MACINTYRE
CPA of Application No. 09/045,507
Original Filed: March 20, 1998
For: CHIP SCALE PACKAGES

Group Art Unit: 2814

Examiner: D. Wille

PRELIMINARY AMENDMENT

2001 Ferry Building
San Francisco, CA 94111
(415) 433-4150

EXPRESS MAIL CERTIFICATE

I hereby certify that this correspondence is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service, Express Mail mailing label number EL254114001, under 37 CFR 1.10 on October 10, 2000 and is addressed to: BOX CPA, Assistant Commissioner for Patents, Washington, DC 20231.

BOX CPA
Assistant Commissioner for Patents
Washington, DC 20231

LIMBACH & LIMBACH LLP Date: 10/10/00

By: 
SUSAN OZANNE

Sir:

Please make the following changes in the above-captioned application.

In the Claims:

Please cancel Claims 4, 6, 7, 15, and 17.

Please add the following claims:

--18. A semiconductor package comprising:

a semiconductor wafer having at least one semiconductor die created therein;

a plurality of bond pads formed on a surface of the semiconductor wafer;

a glass sheet having holes formed therein, wherein the size of the